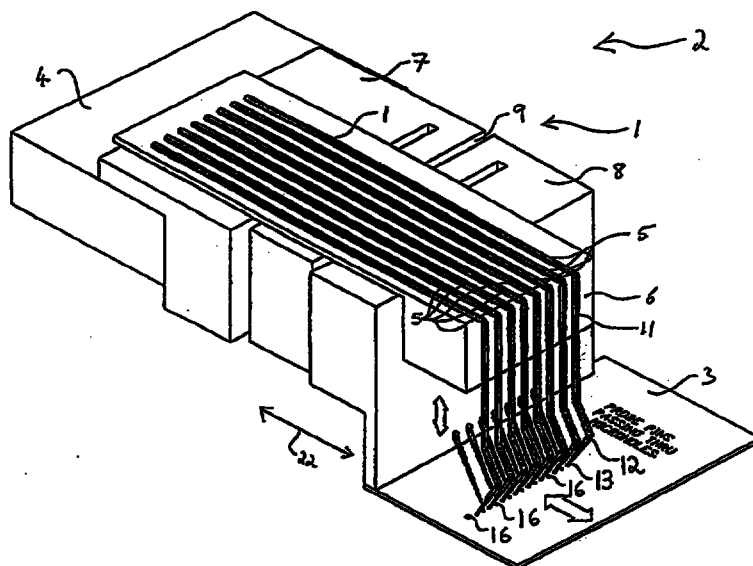




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(54) Title: **INTERFACE DEVICE BETWEEN TESTING EQUIPMENT AND INTEGRATED CIRCUIT**



(57) Abstract

An interface device (2) provides an interface between testing equipment and an integrated circuit to be tested. The interface device (2) includes a body member (7) and a movable member (8) mounted on the body member (7) for movement with respect to the body member (7). A number of elongate contact members (5) are mounted on the movable member (8) for movement with the movable member (8). Each contact member (5) includes a contact end (10), adapted to contact a bond pad of the integrated circuit to be tested, and a body portion (11). The central axis of the body portion (11) and the contact end (10) are substantially parallel to each other.